



# 100% Material Declaration Data Sheet FG256

PK151 (v1.2) September 14, 2006

Material Declaration Data Sheet

**Average Weight: 0.9408 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0749</b>	<b>7.97%</b>
	Silicon	7440-21-3	100.00		0.0749	
<b>Die Attach Material</b>					<b>0.0074</b>	<b>0.78%</b>
	Silver	7440-22-4	78.00		0.0058	
	Resin	Trade Secret	22.00		0.0016	
<b>Mold Compound</b>					<b>0.3748</b>	<b>39.84%</b>
	Epoxy Resins	Trade Secret	12.00		0.0450	
	SiO2	60676-86-0	88.00	Filler	0.3298	
<b>Laminate</b>					<b>0.2085</b>	<b>22.16%</b>
	Laminate	Trade Secret	61.00		0.1272	
	Solder Mask	Trade Secret	17.36		0.0362	
	Copper	7440-50-8	16.00	Metal Layer	0.0334	
	Nickel	7440-02-0	4.80	Metal Layer	0.0100	
	Gold	7440-57-5	0.84	Metal Layer	0.0018	
<b>Bond Wire</b>					<b>0.0043</b>	<b>0.46%</b>
	Gold	7440-57-5	99.00		0.004263581	
	Silver	7440-22-4	0.0025		0.000000108	
	Copper	7440-50-8	0.0005		0.000000022	
	Iron	7439-89-6	0.0005		0.000000022	
	Calcium	7440-70-2	0.0020		0.000000086	
	Palladium	7440-05-3	0.9900		0.000042636	
	Magnesium	7439-95-4	0.0005		0.000000022	
<b>Solder Balls</b>					<b>0.2709</b>	<b>28.79%</b>
	Tin	7440-31-5	63.00		0.170667	
	Lead	7439-92-1	37.00		0.100233	

PK151 (v1.2) September 14, 2006

[www.xilinx.com](http://www.xilinx.com)

1

## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/11/06	1.1	100% Material Declaration.
9/14/06	1.2	Deleted component description.